

ECEN325: Electronics

Spring 2024

Metal-Oxide-Semiconductor Field Effect Transistor (MOSFET)



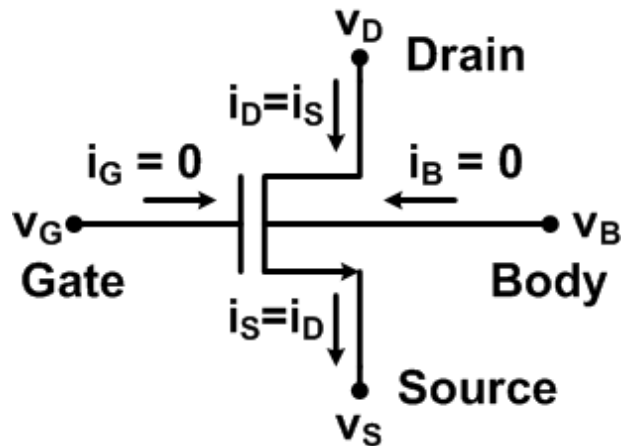
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Announcements & Reading

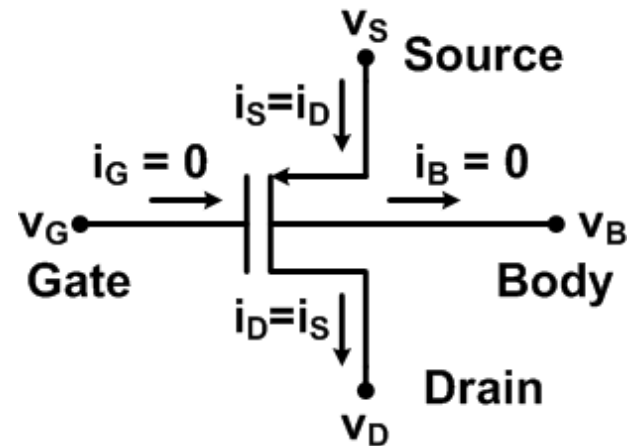
- HW 6 due Apr 25
- MOSFET Reading
 - Razavi Ch6 – MOSFET Models
 - Razavi Ch7 – MOSFET Amplifiers

MOSFET Circuit Symbols

NMOS

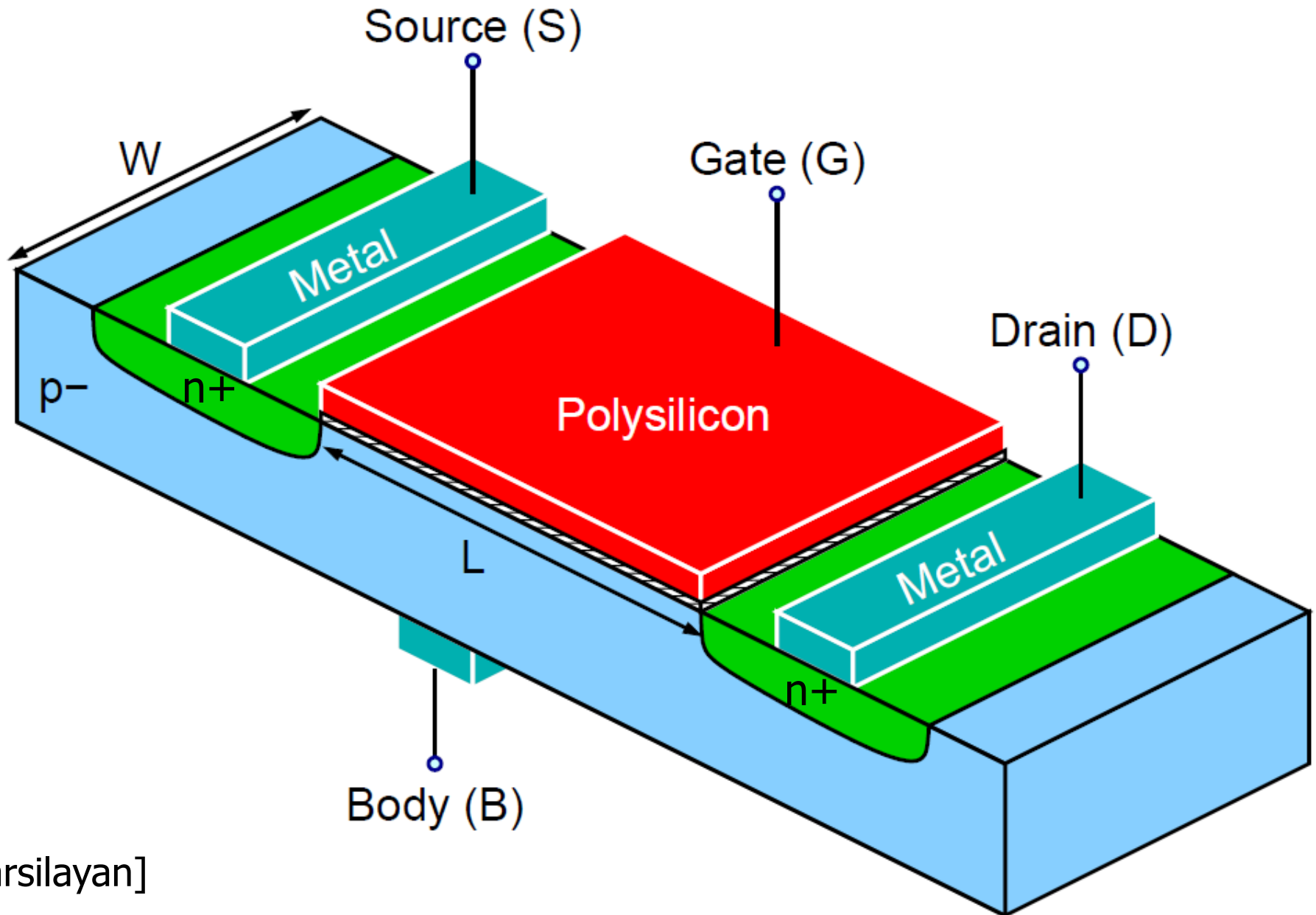


PMOS



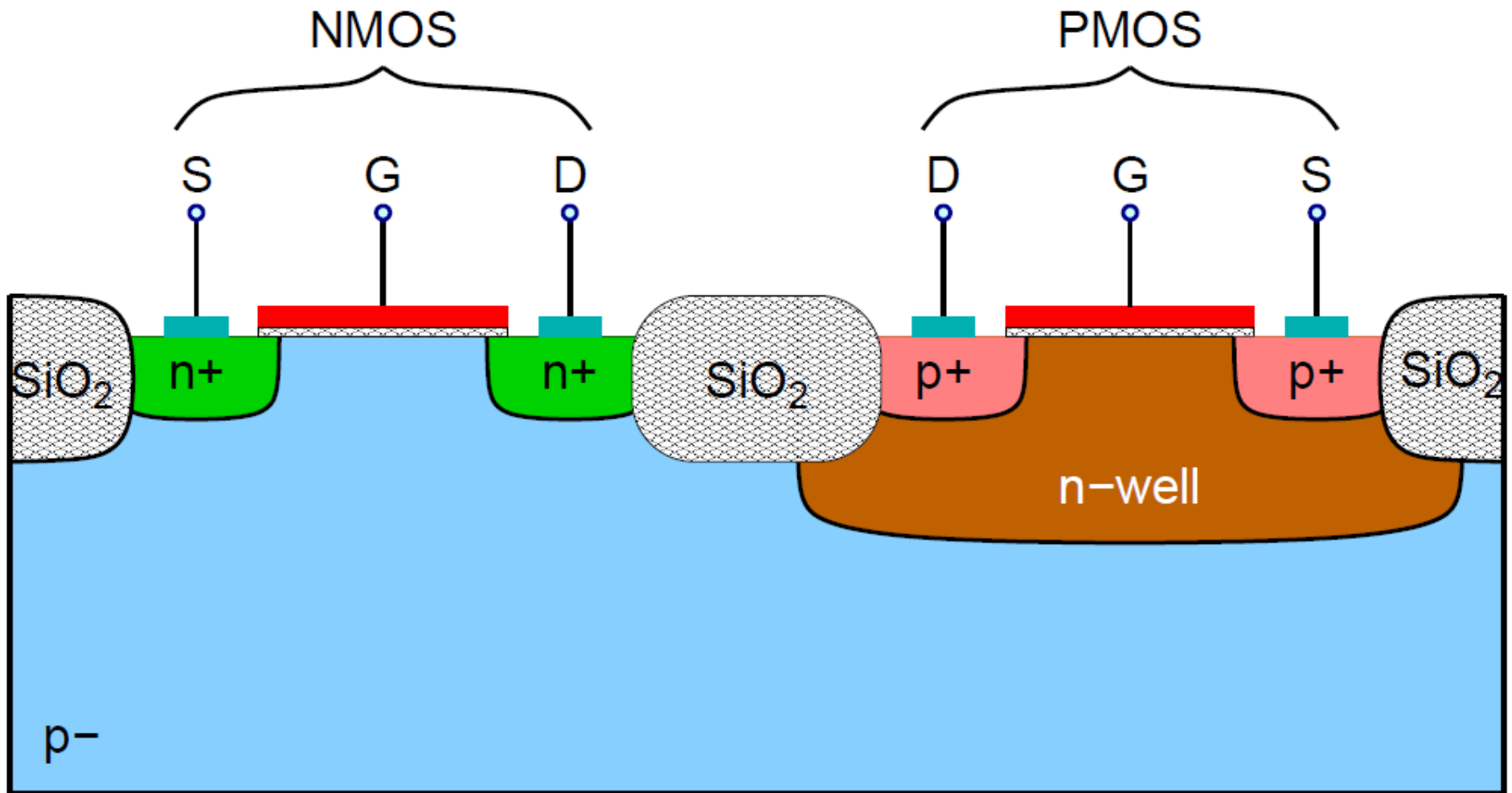
- MOSFETs are 4-terminal devices
 - Drain, Gate, Source, & Body
- Body terminal generally has small impact in normal operation modes, thus device is generally considered a 3-terminal device
 - Drain, Gate, and Source are respectively similar to the Collector, Base, and Emitter of the BJT
- 2 complementary MOSFETs: NMOS, PMOS

NMOS Physical Structure



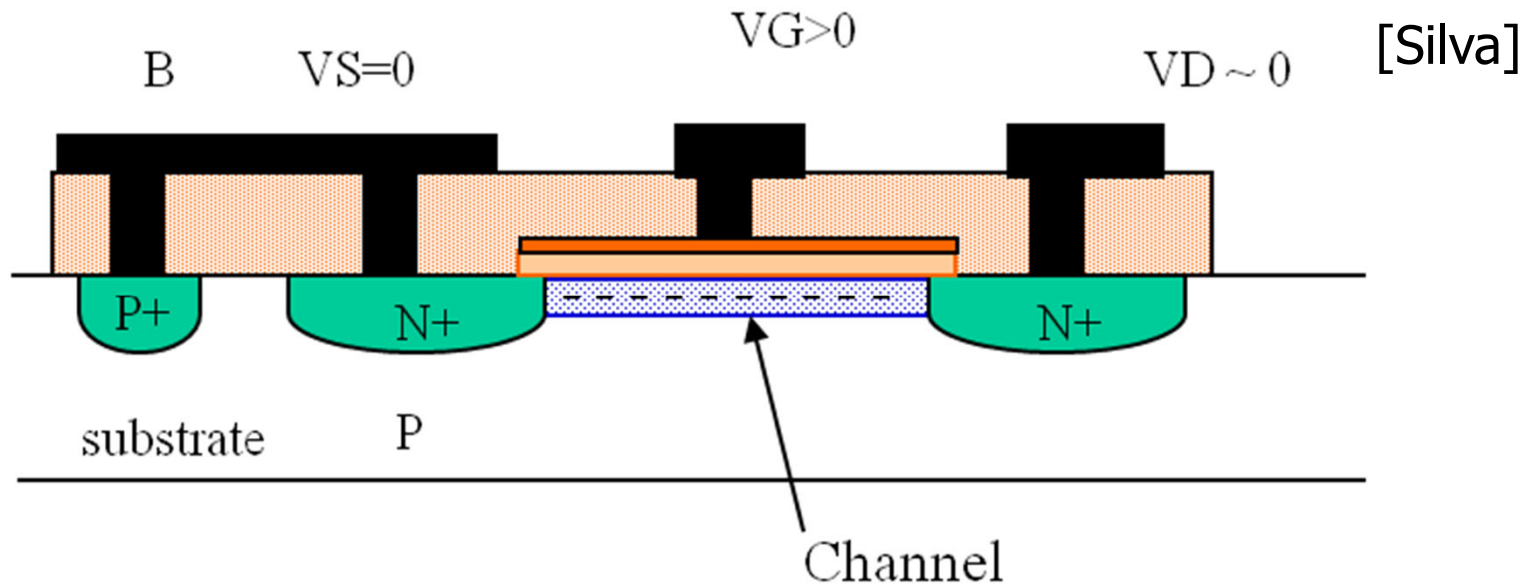
[Karsilayan]

CMOS Physical Structure



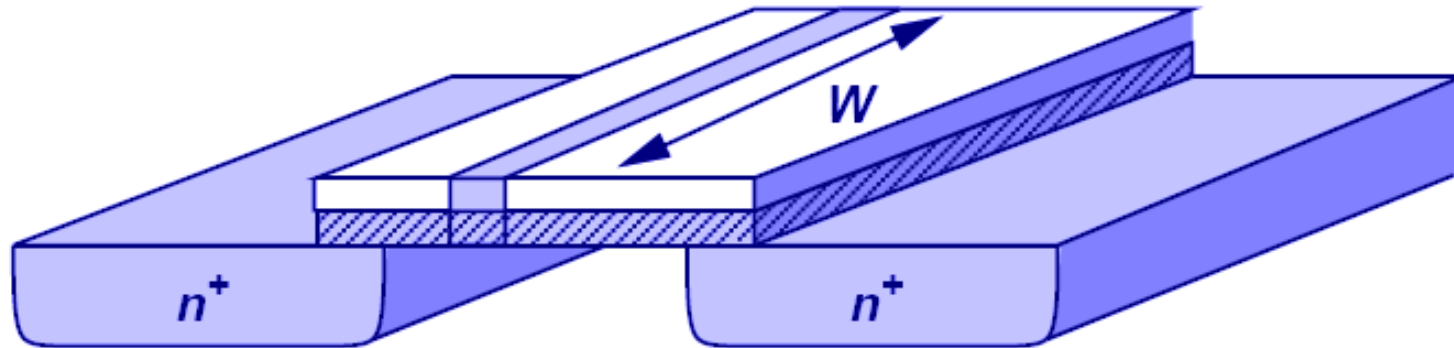
[Karsilayan]

V_{TH} Definition



- The threshold voltage, V_{TH} , is the voltage at which an “inversion layer” is formed
 - For an NMOS this is when the concentration of electrons equals the concentration of holes in the p^- substrate

Drain Current Derivation: Channel Charge Density



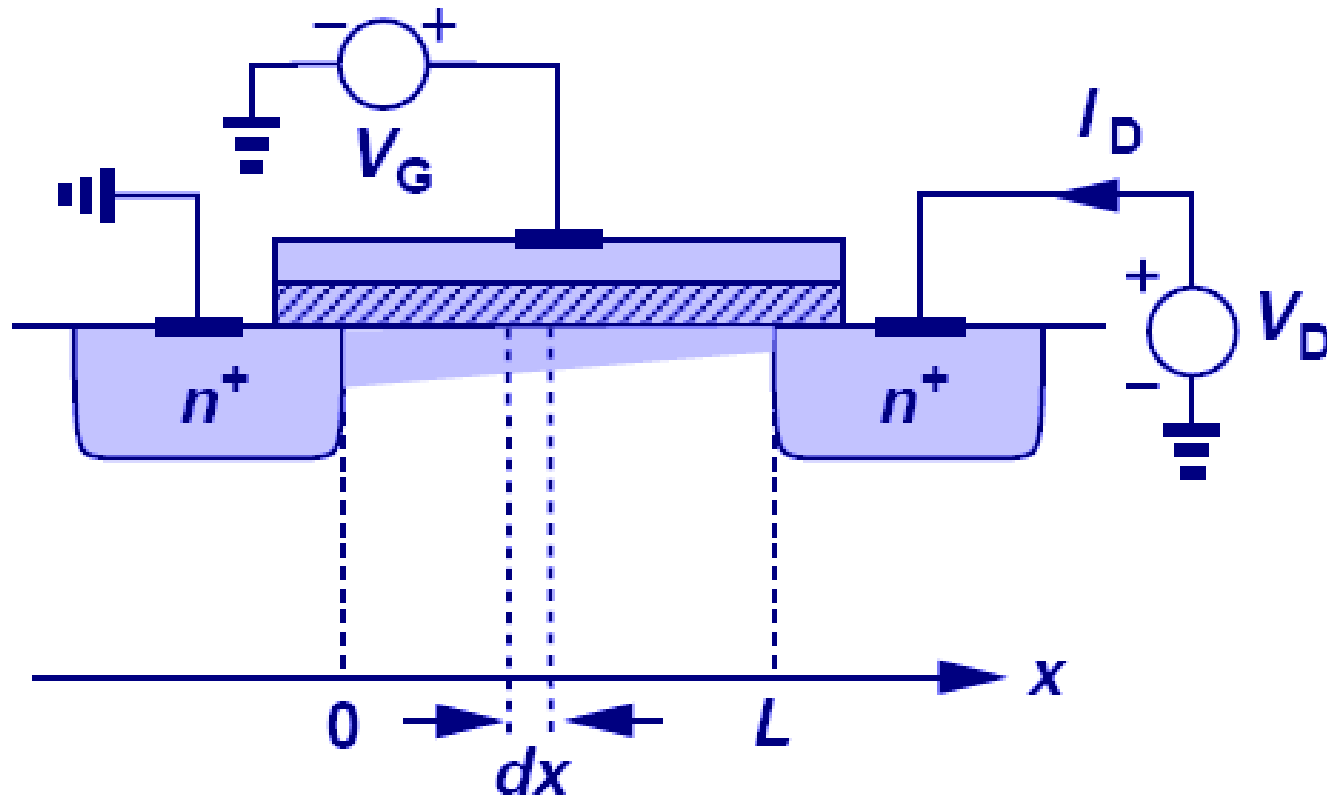
[Razavi]

$$Q = WC_{ox}(V_{GC} - V_{TH})$$

where Capacitance per unit gate area : $C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$

- **The incremental channel charge density is equal to the gate capacitance times the gate-channel voltage in excess of the threshold voltage.**

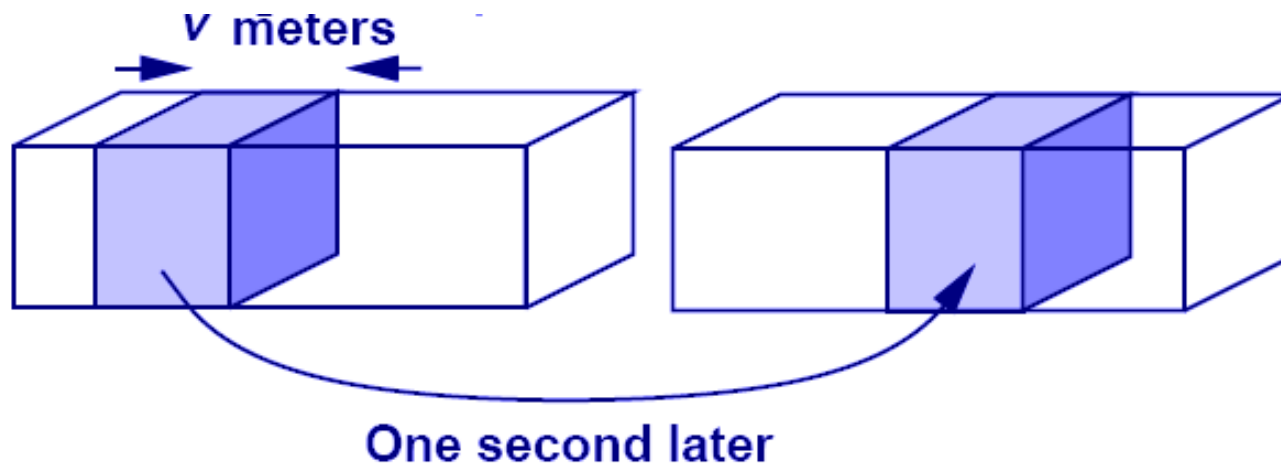
Drain Current Derivation: Charge Density at a Point



$$Q(x) = WC_{ox} [V_{GS} - V(x) - V_{TH}]$$

- Let x be a point along the channel from source to drain, and $V(x)$ its potential; the expression above gives the charge density (per unit length).

Drain Current Derivation: Charge Density and Current

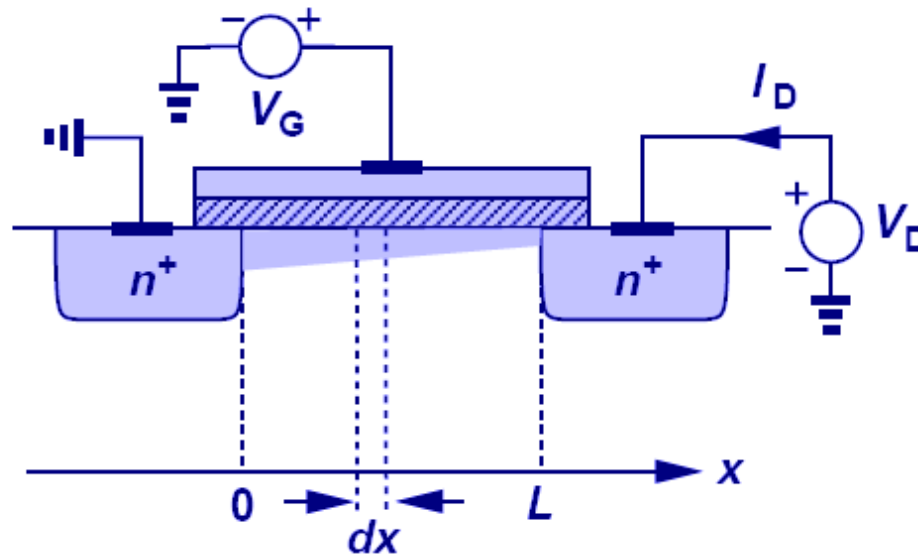


[Razavi]

$$I = Q \cdot v$$

- **The current that flows from source to drain (electrons) is related to the charge density in the channel by the charge velocity.**

Drain Current Derivation: Triode Region (Small V_{DS}) Current Equation



[Razavi]

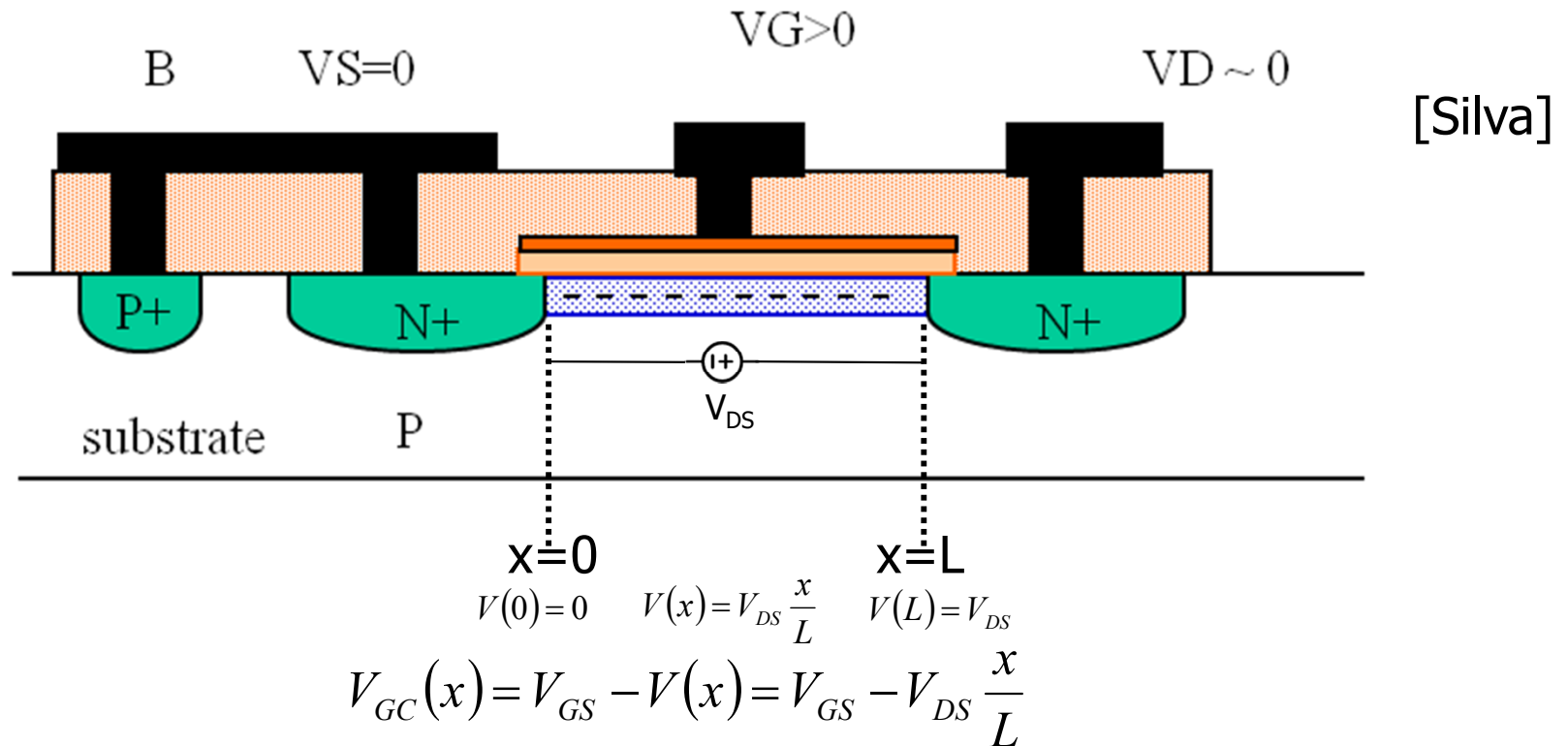
Electron Velocity: $v = +\mu_n \frac{dV}{dx}$

$$I_D = Q(x)v = WC_{ox} [V_{GS} - V(x) - V_{TH}] \mu_n \frac{dV(x)}{dx}$$

$$\int_{x=0}^{x=L} I_D dx = \int_{V(x)=0}^{V(x)=V_{DS}} \mu_n C_{ox} W [V_{GS} - V(x) - V_{TH}] dV(x)$$

$$I_D = \mu_n C_{ox} \frac{W}{L} \left[V_{GS} - V_{TH} - \frac{1}{2} V_{DS} \right] V_{DS}$$

Triode or Linear Region



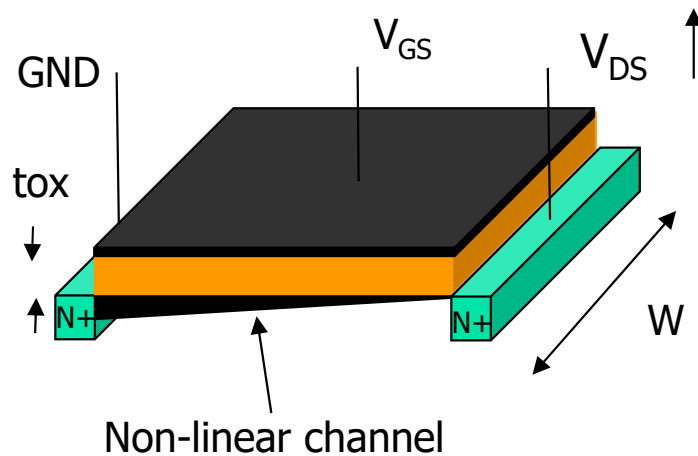
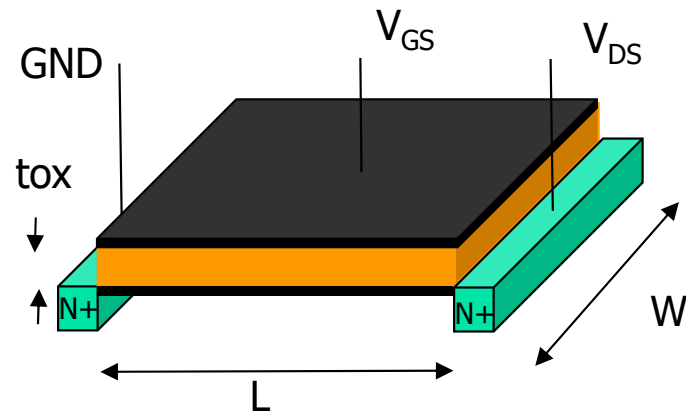
- Channel depth and transistor current is a function of the overdrive voltage, $V_{GS} - V_{Tn}$, and V_{DS}
- Because V_{DS} is small, V_{GC} is roughly constant across channel length and channel depth is roughly uniform

$$I_{DS} = \frac{W}{L} \mu_n C_{OX} (V_{GS} - V_{Tn} - 0.5V_{DS}) V_{DS}$$


 For small V_{DS}

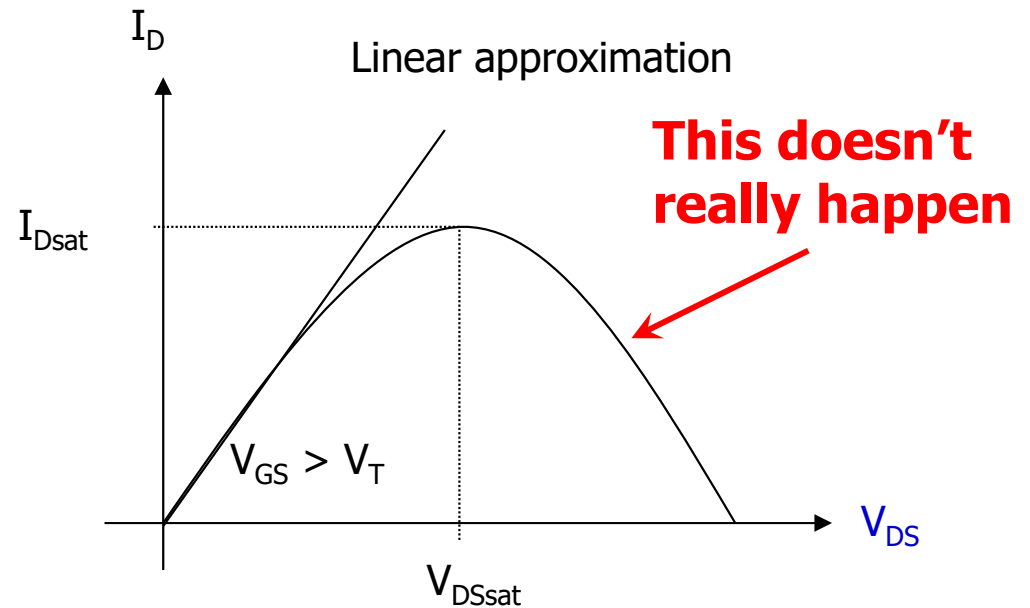
$$R_{DS} \approx \frac{1}{\frac{W}{L} \mu C_{ox} (V_{GS} - V_{Tn})}$$

MOS Equations in Triode Region (Large V_{DS})



Drain current: Expression used in SPICE level 1

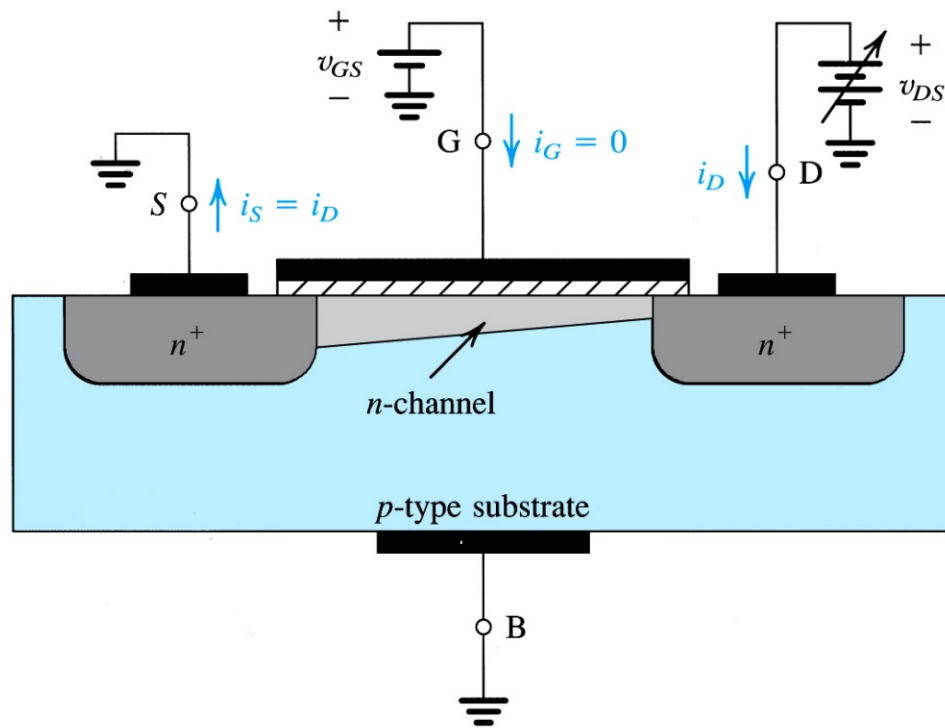
$$I_{DS} = \frac{W}{L} \mu_n C_{OX} (V_{GS} - V_{Tn} - 0.5V_{DS}) V_{DS}$$



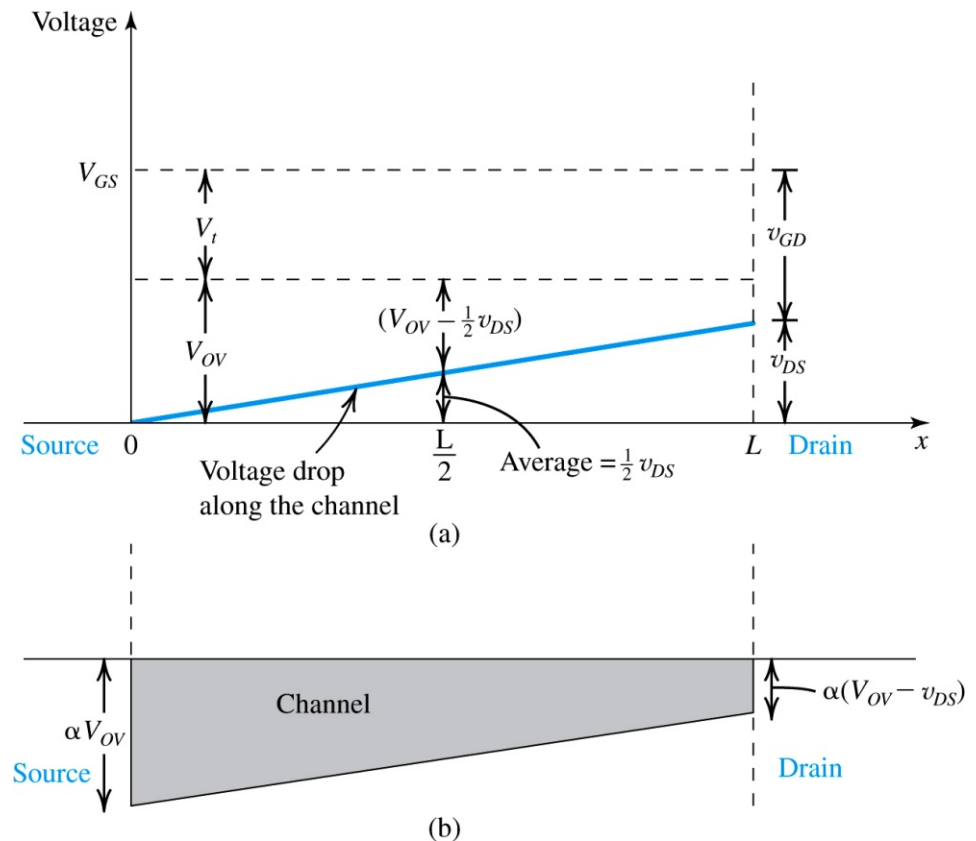
$$V_{DSsat} = V_{GS} - V_{Tn}$$

Triode Region Channel Profile

[Sedra/Smith]

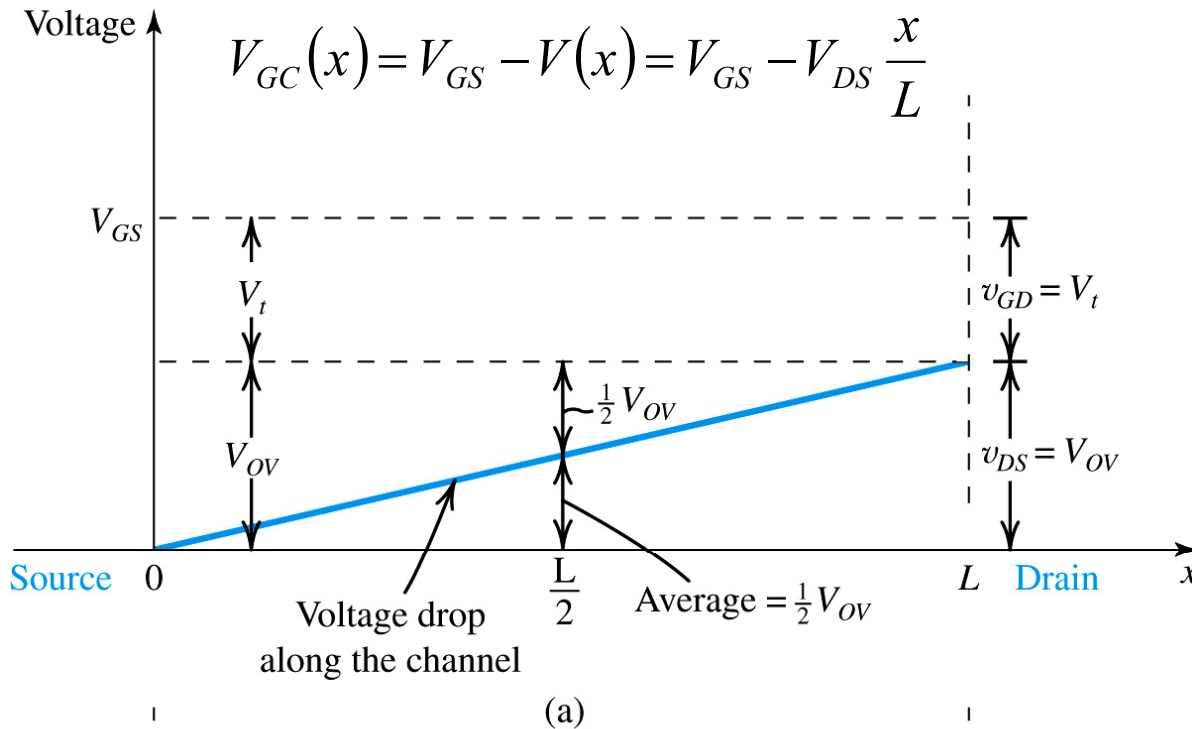


$$V_{GC}(x) = V_{GS} - V(x) = V_{GS} - V_{DS} \frac{x}{L}$$

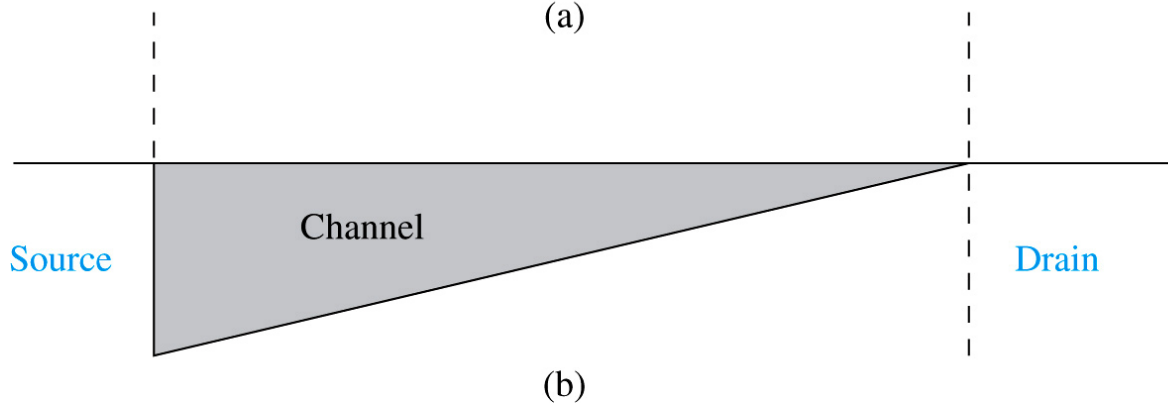


- If V_{GC} is always above V_T throughout the channel length, the transistor current obeys the triode region current equation

Saturation Region Channel Profile

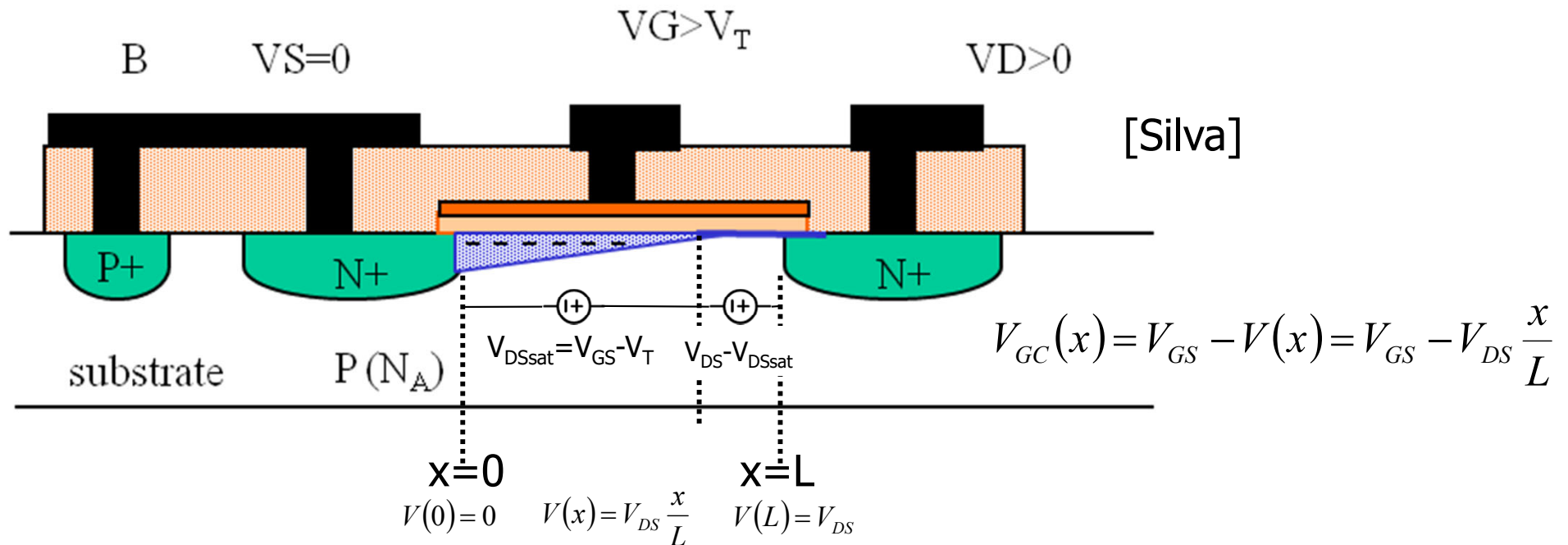


- When $V_{DS} \geq V_{GS} - V_{TH} = V_{OV}$, V_{GC} no longer exceeds V_{TH} , resulting in the channel "pinching off" and the current saturating to a value that is no longer a function of V_{DS} (ideally)



[Sedra/Smith]

Saturation Region



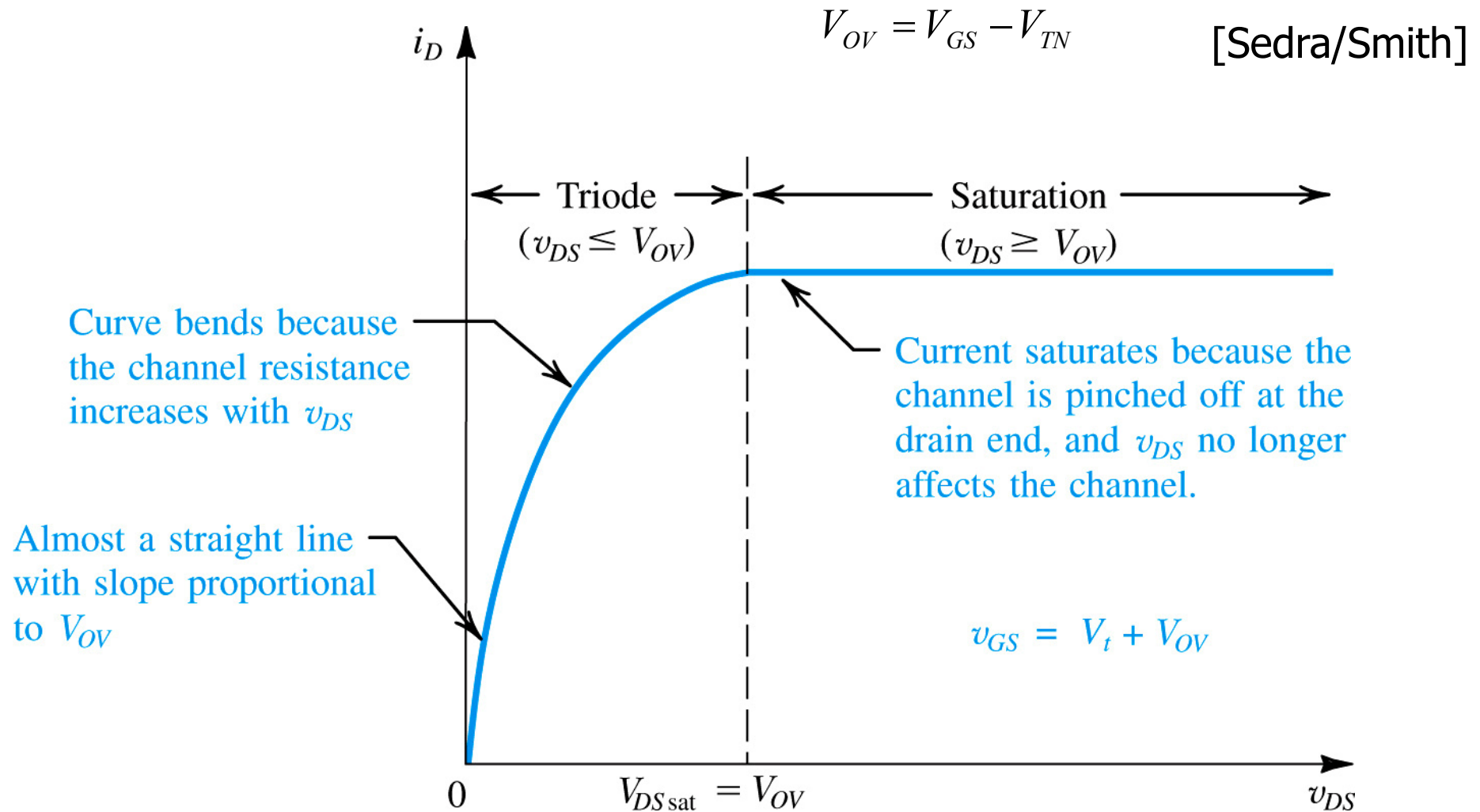
- Channel “pinches-off” when $V_{DS} = V_{GS} - V_{TH}$ and the current saturates
- After channel charge goes to 0, the high lateral field “sweeps” the carriers to the drain and drops the extra V_{DS} voltage

$$I_{DS} = \mu_n C_{OX} \frac{W}{L} \left(V_{GS} - V_{Tn} - \frac{V_{DS}}{2} \right) V_{DS} \Big|_{V_{DS} = V_{GS} - V_{Tn}}$$

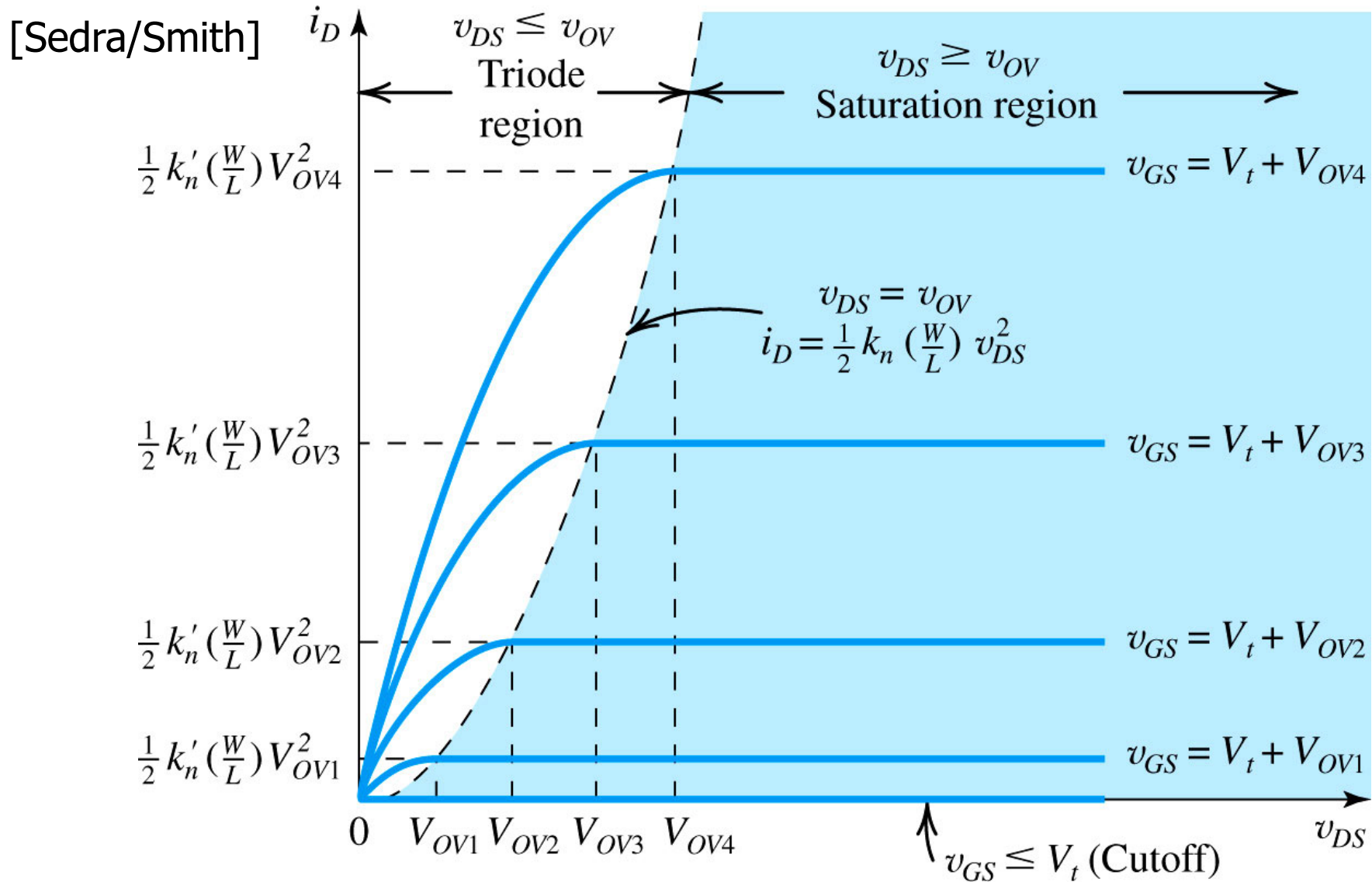
$$V_{DSsat} = V_{GS} - V_{Tn}$$

$$I_{DS} = \frac{\mu_n C_{OX} W}{2 L} (V_{GS} - V_{Tn})^2$$

NMOS $I_D - V_{DS}$ Characteristics

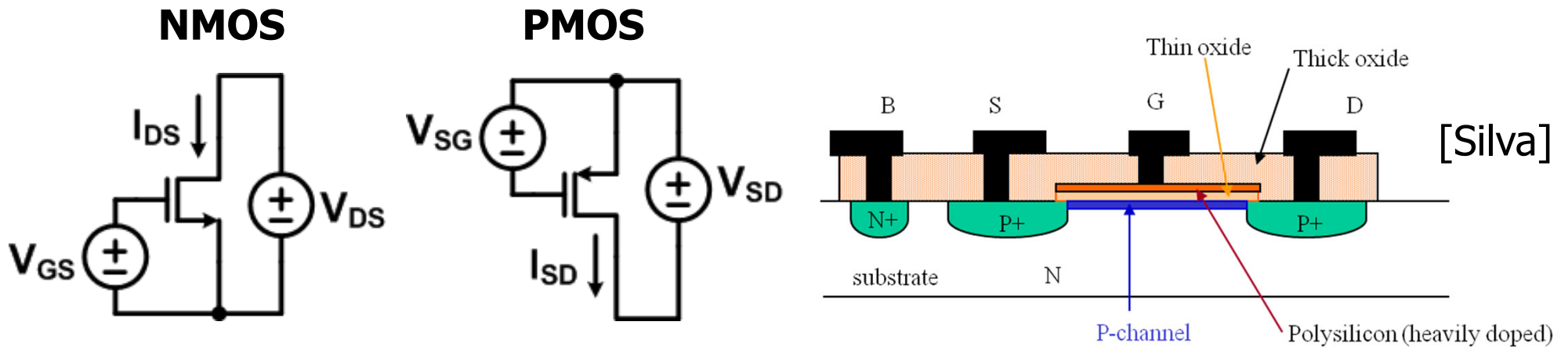


MOS "Large-Signal" Output Characteristic



Note: $V_{ov} = V_{GS} - V_T$

What about the PMOS device?



- The current equations for the PMOS device are the same as the NMOS **EXCEPT** you swap the current direction and all the voltage polarities

NMOS

Linear:
$$I_{DS} = \frac{W}{L} \mu_n C_{OX} (V_{GS} - V_{Tn} - 0.5V_{DS}) V_{DS}$$

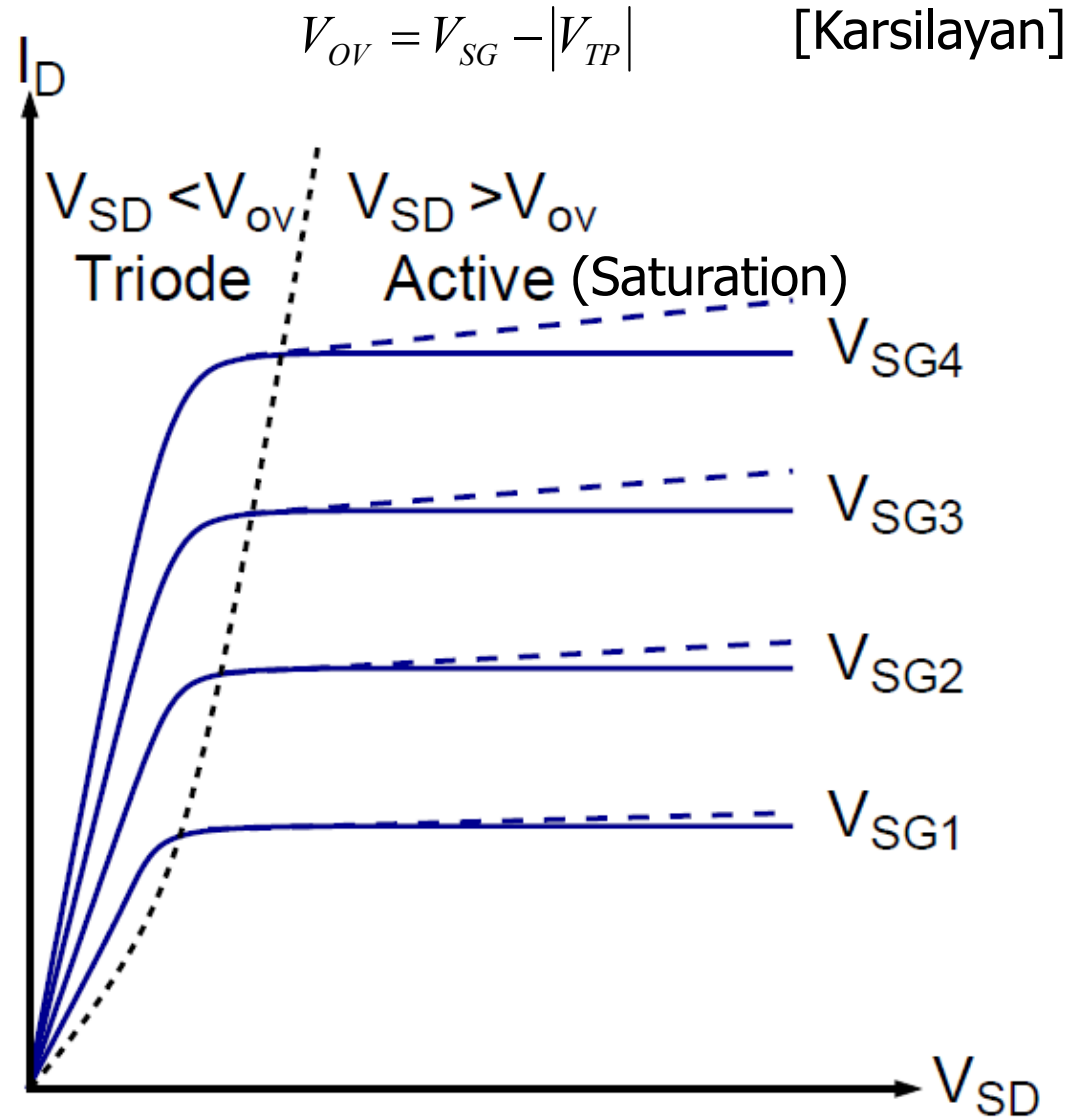
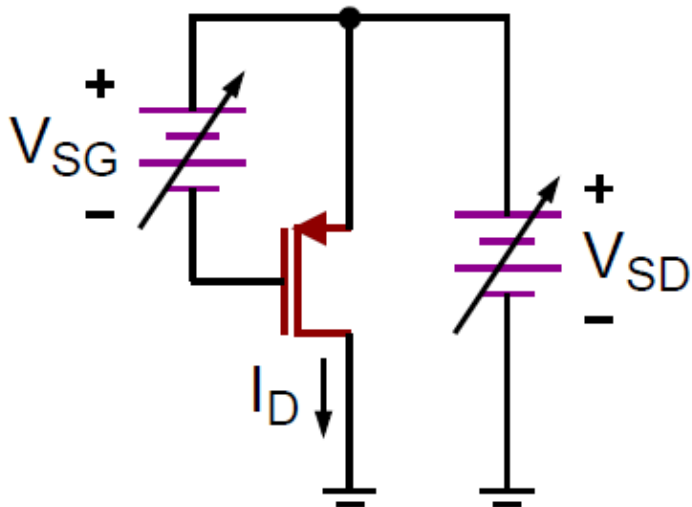
Saturation:
$$I_{DS} = \frac{W}{2L} \mu_n C_{OX} (V_{GS} - V_{Tn})^2$$

PMOS

Linear:
$$I_{SD} = \frac{W}{L} \mu_p C_{OX} (V_{SG} - |V_{Tp}| - 0.5V_{SD}) V_{SD}$$

Saturation:
$$I_{SD} = \frac{W}{2L} \mu_p C_{OX} (V_{SG} - |V_{Tp}|)^2$$

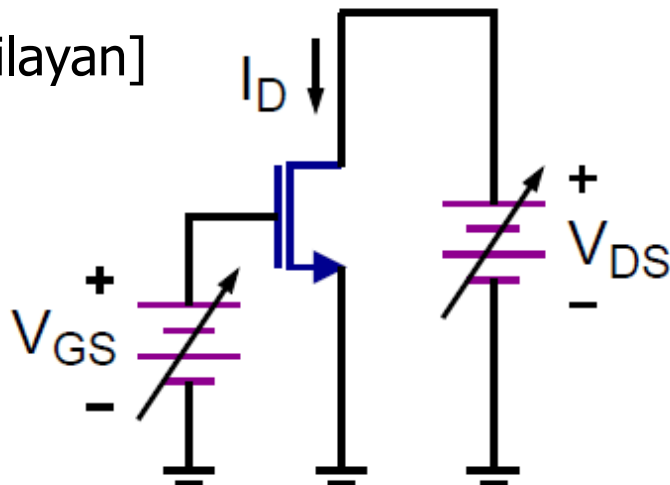
PMOS $I_D - V_{SD}$ Characteristics



NMOS DC Operation (w/ infinite r_{out})

Region	Bias Condition	I_{DS}
Cutoff	$V_{GS} < V_{TN}$	$I_{DS} = 0$
Triode (Linear)	$V_{GS} > V_{TN}, V_{DS} < V_{GS} - V_{TN}$	$I_{DS} = \mu_n C_{ox} \frac{W}{L} \left(V_{GS} - V_{TN} - \frac{V_{DS}}{2} \right) V_{DS}$
Saturation (Active)	$V_{GS} > V_{TN}, V_{DS} > V_{GS} - V_{TN}$	$I_{DS} = \frac{\mu_n C_{ox}}{2} \frac{W}{L} (V_{GS} - V_{TN})^2$

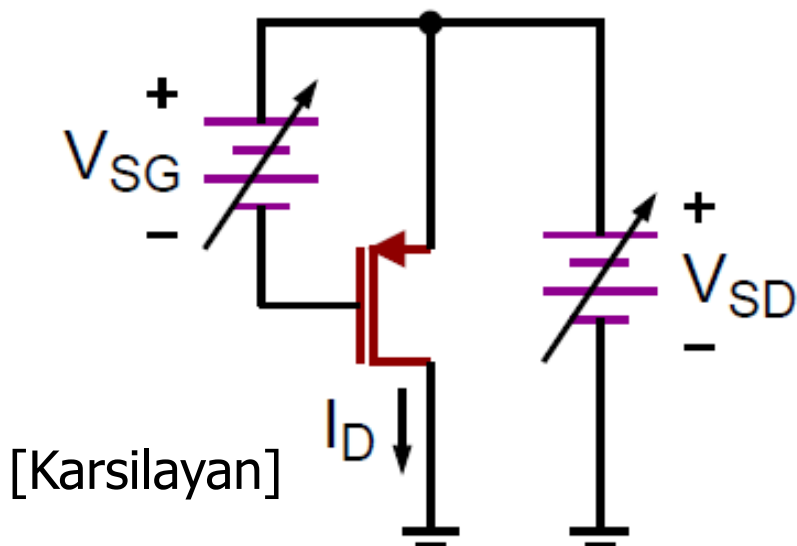
[Karsilayan]



- In transistor model, often combine $\mu_n C_{ox}$ term as a parameter KP_N with units A/V^2
- In lab, we combine $\mu_n C_{ox} (W/L)$ term as a parameter β_N with units A/V^2

PMOS DC Operation (w/ infinite r_{out})

Region	Bias Condition	I_{SD}
Cutoff	$V_{SG} < V_{TP} $	$I_{SD} = 0$
Triode (Linear)	$V_{SG} > V_{TP} , V_{SD} < V_{SG} - V_{TP} $	$I_{SD} = \mu_p C_{ox} \frac{W}{L} \left(V_{SG} - V_{TP} - \frac{V_{SD}}{2} \right) V_{SD}$
Saturation (Active)	$V_{SG} > V_{TP} , V_{SD} > V_{SG} - V_{TP} $	$I_{SD} = \frac{\mu_p C_{ox}}{2} \frac{W}{L} (V_{SG} - V_{TP})^2$



- In transistor model, often combine $\mu_p C_{ox}$ term as a parameter KP_p with units A/V^2
- In lab, we combine $\mu_p C_{ox} (W/L)$ term as a parameter β_p with units A/V^2